

## Zoom Q/A Schedule – Sorted by Session Number

| Session   | Zoom Q/A date time (ET) |
|---|-------------------------|
| Session 1: 2D and 3D Chiplets Interconnects in FO-WLP/PLP                                       | June 24, 10:00 AM       |
| Session 2: Wafer/Panel Level System Integration and Process Advances                            | June 24, 10:00 PM       |
| Session 3: Advanced Heterogenous Chiplet and Integration for HPC                                | June 24, 9:00 PM        |
| Session 4: Heterogeneous Integration Using 2.xD/3D Packaging Technologies                       | June 23, 9:00 PM        |
| Session 5: Technologies for Advanced Substrates and Flip-Chip Bonding                           | June 24, 9:00 AM        |
| Session 6: Advanced Optoelectronics Packaging   | June 23, 1:00 PM        |
| Session 7: 3D TSV and Interposer  | June 30, 11:00 AM       |
| Session 8: Chiplet Integration and Fan-Out Interconnections                                     | June 21, 10:00 AM       |
| Session 9: Advances in Cu Bonding   | June 28, 8:00 PM        |
| Session 10: Surface Preparation for Cu Bonding  | June 30, 9:00 PM        |
| Session 11: Advanced Chip to Chip/Package Interconnections for 3D and Heterogeneous Integration | June 29, 9:30 AM        |
| Session 12: Flexible Interconnects and Low-Temperature Sintering                                | June 23, 6:00 PM        |
| Session 13: Dielectric Materials for High-Speed Wireless Communications                         | June 24, 9:30 AM        |
| Session 14: Enhancements in Sintering Technology and Power Applications                         | June 30, 5:00 PM        |
| Session 15: Material and Process Advancements for Interconnects and Metallurgy Reliability      | June 21, 8:30 PM        |
| Session 16: Innovation on Bonding and Hybrid Bonding Materials and Processing                   | June 22, 9:00 PM        |
| Session 17: Latest Trends in Fan-Out Packaging and Substrate Technology                         | July 1, 8:00 AM         |
| Session 18: Emerging Technology Advancements in Applications and Processing                     | June 22, 6:00 PM        |
| Session 19: Enhanced Reliability Characterization and Methodologies                             | June 28, 10:30 AM       |
| Session 20: Reliability of Automotive Electrification and Autonomous Electronic Components      | June 23, 10:00 AM       |
| Session 21: Advances in Interconnect Reliability  | June 29, 10:00 AM       |
| Session 22: Advanced Package Modeling and Reliability   | June 30, 10:00 AM       |
| Session 23: Heterogeneous Integration Processes and Manufacturing                               | June 25, 11:30 AM       |
| Session 24: Fan-Out Wafer Level Packaging Developments and Applications                         | June 23, 9:30 AM        |
| Session 25: Advances in Assembly Methods  | June 23, 2:30 PM        |
| Session 26: Antenna-in-Package for 5G/6G and Radar Systems                                      | June 21, 8:00 AM        |
| Session 27: Novel High-Frequency Integrated Modules and Systems                                 | June 22, 4:00 PM        |
| Session 28: High-Speed Signal Integrity and Interconnections                                    | June 22, 10:00 AM       |
| Session 29: 3D Power Components and Power Integrity   | June 28, 11:00 AM       |
| Session 30: Package to System Level Thermo-Mechanical Reliability Modeling                      | June 21, 12:00 PM       |
| Session 31: Analyses on Chip Package Interaction and Thermal Management for Heterointegration   | June 23, 11:00 AM       |
| Session 32: Novel Approaches for Reliability and Process Modeling                               | June 29, 8:00 PM        |
| Session 33: Flexing and Warpage Characterization and Modeling                                   | June 23, 10:30 AM       |
| Session 34: Flexible Hybrid Sensors and Electronics   | June 21, 11:00 AM       |
| Session 35: Emerging Quantum and Advanced Interconnects   | June 24, 11:00 AM       |
| Session 36: Packaging, Machine Learning, and Integration Technologies                           | June 28, 9:00 AM        |
| Session 37: Photonics, 5G, mm Wave Applications & Techniques                                    | June 24, 1:00 PM        |
| Session 38: Reliability Analysis of New Materials in Modern Packaging                           | June 29, 9:00 AM        |
| Session 39: High Speed Channel Design, Power Delivery and Analysis                              | June 25, 9:00 AM        |
| Session 40: Materials and Techniques in High Speed Interconnects                                | June 22, 9:00 AM        |
| Session 41: Characterization and Performance Analysis of Packaging Materials                    | June 30, 8:00 PM        |
| Session 42: Topics in Advanced Packaging  | June 28, 10:00 AM       |
| Session 43: Manufacturing Techniques for Emerging Packaging Requirements                        | June 25, 4:00 PM        |
| Session 44: Thermo-mechanical Analysis for Reliability in Packaging Technology                  | July 1, 8:00 PM         |
| Session 45: Heterogeneous Integration, Flex and Emerging Technologies                           | June 23, 9:00 AM        |
| Session 46: Student Session   | June 22, 10:30 AM       |

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| Session 17: Latest Trends in Fan-Out Packaging and Substrate Technology                         | July 1, 8:00 AM         |
| Session 44: Thermo-mechanical Analysis for Reliability in Packaging Technology                  | July 1, 8:00 PM         |